Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	"6507116".pn.	USPAT	OR	ON	2005/07/13 07:12
S1	0	10/753914	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 11:07
S2	1	09/948877	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 15:53
S3	1736	"KONINKLIJKE PHILIPS".as.	USPAT	OR	ON	2003/08/19 13:35
S4	2094408	(microchip micro adj chip chip integrated adj circuit die ic semiconductor adj (device element structure component module))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 07:22
S5	314556	(heatsink ((heat thermal$2) near (sink$4 spread$3 dissipat$3 conducting conductive radiat$4)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 07:19
S6	2247483	(shield$3 protect$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 19:19
S7	2471633	S5 S6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 19:19
S8	330305	(((printed adj circuit PC wiring) adj (board card module)) pcb PWB motherboard mother adj board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 19:20
S9	5186500	base substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 19:20
S10	5363869	S8 S9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 19:22

S11	348229	S4 near9 S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 19:26
S12	95542	S4 near9 S7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 19:27
S13	2	"5936304".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 19:28
S14	24470	S11 same S12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 19:29
S15	3057305	(encapsula$3 encapsulation mold$3 resin epoxy potting gel)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/10 19:30
S16	6646	S14 same S15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:11
S17	3246070	"11" same "12"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:12
S18	2094408	(microchip micro adj chip chip integrated adj circuit die ic semiconductor adj (device element structure component module))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:12
S19	314556	(heatsink ((heat thermal$2) near (sink$4 spread$3 dissipat$3 conducting conductive radiat$4)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:12
S20	2247483	(shield$3 protect$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:12

S21	2471633	S19 S20		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:12
S22	330305	(((printed adj circuit PC wiring) adj (board card module)) pcb PWB motherboard mother adj board)		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:12
S23	5186500	base substrate		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:12
S24	5363869	S22 S23		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:12
S25	348229	S18 near9 S24		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:12
S26	95542	S18 near9 S21		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:12
S27	24470	S25 same S26		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:17
S28	6684423	(open$5 hole aperture groove cavity perforat$4)		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 07:40
S29	140166	S21 near4 S28		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:21
S30	3993	S27 and S29		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:21

S31	25226	flip adj chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:22
S32	4932329	copper cu aluminum al	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:25
S33	105237	S21 near8 S32	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:29
S34	1570	S30 and S33	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:29
S35	451	S34 and S31	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:30
S36	718522	bump ball	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:31
S37	50915	S36 near9 S18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:35
S38	1753597	(adhe$6 glue)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:36
S39	4156	S18 with S19 with S38	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:40
S40	223	S35 and S39	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:41

S41	192	S40 and S37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 07:41
S42	1	10/766210	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 09:03
S43	24844	dovetail	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 09:03
S44	57	S19 near9 S43	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 09:04
S45	0	S44 and S41	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 09:03
S46	275	S21 near9 S43	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 09:09
S47	0	S46 and S41	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 09:05
S48	5	S30 and S46	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 09:06
S49	7	S27 and S46	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 09:09
S50	41545	S25 and S26	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 09:09

S51	396	S21 with S43	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 09:10
S52	16	S50 and S51	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/11 09:10
S53	1	10/766210	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 17:41
S54	7	"10242355" "09306954"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 07:25
S55	1865953	(chip carrier flip adj chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:46
S56	326069	(heatsink ((heat thermal$2) near (sink$4 spread$3 dissipat$3 conducting conductive radiat$4)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:02
S57	28825	dovetail dove near tail	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 07:22
S58	2167680	(microchip micro adj chip chip integrated adj circuit die ic semiconductor adj (device element structure component module))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 07:22
S59	7	"10242355" "09306954"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 11:56
S60	111	"YOSHIKAWA, YASUHIRO".in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 10:44

S61	808498	hitachi.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 07:27
S62	6	S60 and S61	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 07:27
S63	6862761	(open$5 hole aperture groove cavity perforat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 07:41
S64	36	S56 near6 S57	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:04
S65	2608773	lid cap cover	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:02
S66	708	S65 near6 S57	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:05
S67	3142559	(encapsula$3 encapsulation mold$3 resin epoxy potting gel)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:08
S68	76	S66 same S67	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:06
S69	7	S68 and S58	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:07
S70	1	S68 and S56	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:06

S71	1169762	circular diamond	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:11
S72	529481	cone conical	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:13
S73	17996	diamond near shap$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:14
S74	50	S56 with S73	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:14
S75	81	S56 with S57	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:15
S76	38	S75 and S67	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:21
S77	186	S72 with S73	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:21
S78	231	S74 S77	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:22
S79	6	S78 same S67	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:22
S80	82	S78 and S67	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:22

S81	29	S80 and S58	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:27
S82	2	"6507116".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:27
S83	1	("6507116").URPN.	USPAT	OR	ON	2005/06/14 08:27
S84	14	("4151547" | "5041902" | "5111359" | "5247426" | "5537342" | "5619070" | "5625226" | "5705851" | "5726079" | "5736785" | "5760465" | "5777847" | "5868887" | "5883430").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/14 08:33
S85	63	S77 and S67	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/14 08:36
S86	122056	diamond	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/14 08:36
S87	1516001	S56 S65	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/14 08:37
S88	3755	S86 with S87	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/14 08:37
S89	401327	anchor$3	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/14 08:37
S90	2645928	secur$4	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/14 08:38
S91	3	S88 with S89	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/14 08:38
S92	67	S88 with S90	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/14 08:45
S93	602433	invert$4	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/14 08:46
S94	3966298	(align$4 angle$4 oblique$4 inclin$4 bevel$4 taper$4 slant$4 slop$4 V adj shaped)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:00

S95	774191	S63 near6 S94	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:51
S96	75106	S95 same S87	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:52
S97	422440	S67 with S63	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 08:55
S98	11853	S96 and S97	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 09:00
S99	3054	S96 same S97	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 09:00
S100	347	S99 same S58	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 09:02
S101	4	("6534859").URPN.	USPAT	OR	ON	2005/06/14 09:50
S102	16	("5227663" | "5371404" | "5641987" | "5785799" | "5834839" | "5866953" | "5872395" | "5891753" | "5977626" | "6069023" | "6150193" | "6191360" | "6201301" | "6229702" | "6316829" | "6462405").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/14 09:51
S103	6	("6433420").URPN.	USPAT	OR	ON	2005/06/14 09:54
S104	2	("6432749").URPN.	USPAT	OR	ON	2005/06/14 09:56
S105	3	("6025642" | "6049123" | "6168970").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/14 09:57
S106	37	("6060778").URPN.	USPAT	OR	ON	2005/06/14 10:05
S107	111	"YOSHIKAWA, YASUHIRO".in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 10:42

S10 8	30536	"YOSHIKAWA".in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 10:44
S10 9	1978	S61 and S108	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 10:44
S11 0	123	S61 and S108	USPAT	OR	ON	2005/06/14 10:44
S11 1	418224	hook	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 11:57
S11 2	368	S56 near6 S111	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 11:57
S11 3	49	S112 same S58	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 12:06
S11 4	242	"Lin, Chang-Fu".in. "Pu, Han-Ping".in. "Hsiao, Cheng-Hsu".in. "Huang, Chien Ping".in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 12:07
S11 5	763	siliconware.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 12:08
S11 6	197	S114 and S115	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 12:08
S11 7	185	S116 and S67	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 12:08
S11 8	182	S117 and S87	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 12:49

S11 9	1914204	S89 S90 fasten$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:06
S12 0	343	S87 with S73	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:09
S12 1	22	S119 with S120	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:08
S12 2	522226	semiconductor adj device	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:10
S12 3	16	S120 and S122	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:13
S12 4	49407	S72 near shaped	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:13
S12 5	2189	S87 with S124	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:14
S12 6	208	S125 with S119	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:14
S12 7	0	S126 and S122	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:14
S12 8	11	S126 and S58	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:15

S12 9	77	S126 and S67	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:19
S13 0	15349	fan adj shaped	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:20
S13 1	446	S87 with S130	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:20
S13 2	25	S131 with S119	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:21
S13 3	218100	wedge	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:21
S13 4	6679	S87 with S133	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:22
S13 5	966	S134 with S119	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:22
S13 6	10	S135 and S122	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:24
S13 7	375	S135 and S67	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:24
S13 8	69	S137 and S58	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:31

S13 9	71180	S95 with S119	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:31
S14 0	6113	S139 with S87	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:32
S14 1	2395	S140 and S67	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:32
S14 2	444	S141 and S58	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:46
S14 3	39	S142 and S122	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:33
S14 4	1724290	(second top upper front main) adj (surface side face)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:47
S14 5	1961690	larger wider bigger	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:47
S14 6	14347	S144 near5 S145	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 14:02
S14 7	77436	S134 S139	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:48
S14 8	71989	S147 with S119	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:51

S149	2	"6380621".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:51
S150	18	("3871015" | "4654966" | "4825284" | "4914551" | "5276289" | "5291064" | "5455457" | "5533256" | "5569960" | "5585671" | "5598036" | "5705850" | "5751060" | "5866951" | "5905636" | "6219543" | "6225695" | "6236568").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/14 13:59
S151	3	("6380621").URPN.	USPAT	OR	ON	2005/06/14 13:59
S152	12	S146 with S148	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 14:03
S153	5	"10242355"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 15:54
S154	0	"YOSHIKAWA, YASUHIRO"".in"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 15:54
S155	111	"YOSHIKAWA, YASUHIRO".in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 15:54
S156	4414429	(align$4 angle$4 oblique$4 inclin$4 bevel$4 taper$4 slant$4 slop$4 V adj shaped) cone nonical wedge fan	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:01
S157	328517	(heatsink ((heat thermal$2) near (sink$4 spread$3 dissipat$3 conducting conductive radiat$4)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:02
S158	2627208	lid cap cover	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:04
S159	2856452	S157 S158	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:04

S16 0	420719	hook	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:04
S16 1	4632356	S156 S160	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:05
S16 2	131767	S159 near4 S161	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:54
S16 3	3160080	(encapsula$3 encapsulation mold$3 resin epoxy potting gel.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:08
S16 4	3137	S162 with S163	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:09
S16 5	27381	flip adj chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:09
S16 6	7	S164 same S165	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:09
S16 7	58	S164 and S165	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:09
S16 8	55	("5473512").URPN.	USPAT	OR	ON	2005/07/12 16:51
S16 9	3	("5241133" | "5311059" | "5346118").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/12 16:53
S17 0	186479	S159 near7 S161	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:54

S17 1	3137	S164 with S170	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:56
S17 2	58	S171 and S165	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:55
S17 3	4803	S163 with S170	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:56
S17 4	4889	S173 and13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:56
S17 5	78	S173 and S165	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 16:56
S17 6	20	S175 not S167	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 17:04
S17 7	2	"6507104".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 17:04
S17 8	13	("5522667" | "5619070" | "5726079" | "5920120" | "5939783" | "5977626" | "6117705" | "6150724" | "6191360" | "6218730" | "6255143" | "6265771" | "6271058").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/12 17:05
S17 9	3	("6507104").URPN.	USPAT	OR	ON	2005/07/12 17:05
S18 0	26	("5883430").URPN.	USPAT	OR	ON	2005/07/12 17:38
S18 1	5	("5404273" | "5510956" | "5619070" | "5625226" | "5672548").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/12 17:43
S18 2	26	("5883430").URPN.	USPAT	OR	ON	2005/07/13 07:11